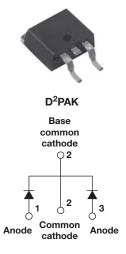


# HEXFRED®, Ultrafast Soft Recovery Diode, 2 x 15 A



PRODUCT SUMMARY						
Package	TO-263AB (D <sup>2</sup> PAK)					
I <sub>F(AV)</sub>	2 x 15 A					
$V_{R}$	600 V					
V <sub>F</sub> at I <sub>F</sub>	1.7 V					
t <sub>rr</sub> (typ.)	19 ns					
T <sub>J</sub> max.	150 °C					
Diode variation	Common cathode					

#### **FEATURES**

- Ultrafast and ultrasoft recovery
- Very low I<sub>RRM</sub> and Q<sub>rr</sub>
- · Specified at operating conditions
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified
- Material categorization:
   For definitions of compliance please see <a href="https://www.vishay.com/doc?99912">www.vishay.com/doc?99912</a>





#### ROHS COMPLIANT HALOGEN FREE

#### **BENEFITS**

- · Reduced RFI and EMI
- · Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- · Reduced parts count

#### **DESCRIPTION**

VS-HFA30TA60CS is a state of the art center tap ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600 V and 15 A per leg continuous current, the VS-HFA30TA60CS is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current (I<sub>RRM</sub>) and does not exhibit any tendency to "snap-off" during the t<sub>b</sub> portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED VS-HFA30TA60CS is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

ABSOLUTE MAXIMUM RATINGS						
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS		
Cathode to anode voltage	$V_{R}$		600	V		
Maximum continuous forward current per leg	1	T <sub>C</sub> = 100 °C	15			
per device	e I <sub>F</sub>		30	^		
Single pulse forward current	I <sub>FSM</sub>		150	А		
Maximum repetitive forward current	I <sub>FRM</sub>		60			
Maximum newer discination	В	T <sub>C</sub> = 25 °C	74	°C		
Maximum power dissipation	$P_D$	T <sub>C</sub> = 100 °C	29	]		
Operating junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		- 55 to + 150	W		

Revision: 27-Aug-12 1 Document Number: 94071





<b>ELECTRICAL SPECIFICATIONS PER LEG</b> (T <sub>J</sub> = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Cathode to anode breakdown voltage	V <sub>BR</sub>	Ι <sub>R</sub> = 100 μΑ	600	-	-		
Maximum forward voltage		I <sub>F</sub> = 15 A		-	1.3	1.7	V
	$V_{FM}$	I <sub>F</sub> = 30 A	See fig. 1	-	1.5	2.0	
		I <sub>F</sub> = 15 A, T <sub>J</sub> = 125 °C		-	1.2	1.6	
Maximum reverse		V <sub>R</sub> = V <sub>R</sub> rated	0 6 0	-	1.0	10	
leakage current	I <sub>RM</sub>	T <sub>J</sub> = 125 °C, V <sub>R</sub> = 0.8 x V <sub>R</sub> rated	See fig. 2	-	400	1000	μΑ
Junction capacitance	C <sub>T</sub>	V <sub>R</sub> = 200 V See fig. 3		-	25	50	pF
Series inductance	L <sub>S</sub>	Measured lead to lead 5 mm from package body		-	8.0	-	nH

<b>DYNAMIC RECOVERY CHARACTERISTICS PER LEG</b> (T <sub>J</sub> = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CO	MIN.	TYP.	MAX.	UNITS		
	t <sub>rr</sub>	$I_F = 1.0 \text{ A}, dI_F/dt = 200$	A/μs, V <sub>R</sub> = 30 V	-	19	-		
Reverse recovery time See fig. 5, 10	t <sub>rr1</sub>	T <sub>J</sub> = 25 °C		-	42	60	ns	
occ lig. 5, 10	t <sub>rr2</sub>	T <sub>J</sub> = 125 °C	I <sub>F</sub> = 15 A dI <sub>F</sub> /dt = 200 A/μs V <sub>R</sub> = 200 V	-	70	90		
Peak recovery current	I <sub>RRM1</sub>	T <sub>J</sub> = 25 °C		-	4.0	6.0	nC A/us	
See fig. 6	I <sub>RRM2</sub>	T <sub>J</sub> = 125 °C		-	6.5	10		
Reverse recovery charge	Q <sub>rr1</sub>	T <sub>J</sub> = 25 °C		-	80	180		
See fig. 7	Q <sub>rr2</sub>	T <sub>J</sub> = 125 °C		-	220	450		
Peak rate of fall of recovery current during t <sub>b</sub> See fig. 8	dI <sub>(rec)M</sub> /dt1	T <sub>J</sub> = 25 °C		-	188	-		
	dI <sub>(rec)M</sub> /dt2	T <sub>J</sub> = 125 °C		-	160	-	-νμ5	

THERMAL - MECHANICAL SPECIFICATIONS PER LEG							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Lead temperature	T <sub>lead</sub>	0.063" from case (1.6 mm) for 10 s	-	-	300	°C	
Junction to case, single leg conducting	В		-	-	1.7		
Junction to case, both legs conducting	R <sub>thJC</sub>		-	-	0.85	K/W	
Thermal resistance, junction to ambient	R <sub>thJA</sub>	Typical socket mount		-	80		
Weight			-	2.0	-	g	
vveignt			-	0.07	-	oz.	
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)	
Marking device		Case style D <sup>2</sup> PAK	HFA30TA60CS			•	

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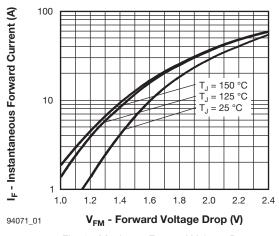


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current (Per Leg)

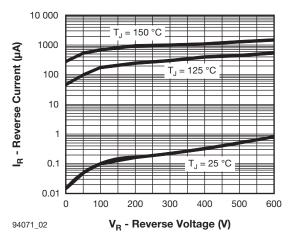


Fig. 2 - Typical Reverse Current vs. Reverse Voltage (Per Leg)

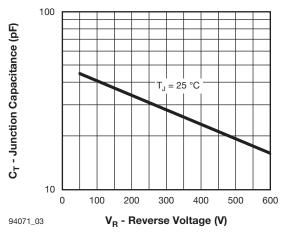


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

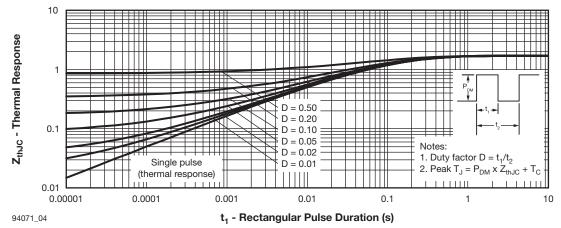


Fig. 4 - Maximum Thermal Impedance Z<sub>thJC</sub> Characteristics (Per Leg)





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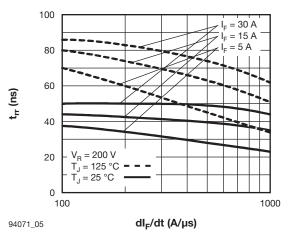


Fig. 5 - Typical Reverse Recovery Time vs. dI<sub>F</sub>/dt (Per Leg)

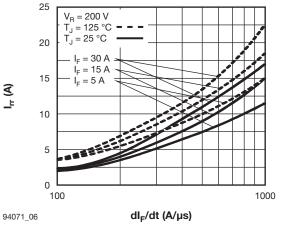


Fig. 6 - Typical Recovery Current vs. dl<sub>F</sub>/dt (Per Leg)

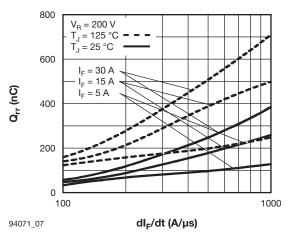


Fig. 7 - Typical Stored Charge vs. dl<sub>F</sub>/dt (Per Leg)

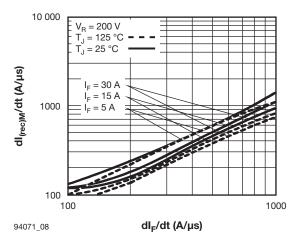


Fig. 8 - Typical dI<sub>(rec)M</sub>/dt vs. dI<sub>F</sub>/dt (Per Leg)

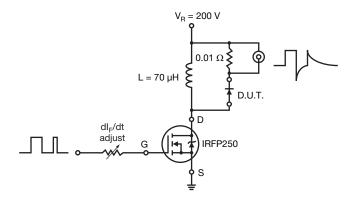
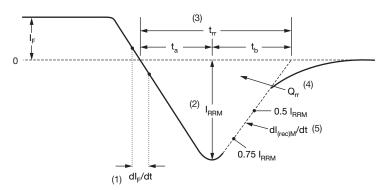


Fig. 9 - Reverse Recovery Parameter Test Circuit



- (1) dl<sub>F</sub>/dt rate of change of current through zero crossing
- (2)  $\rm I_{RRM}$  peak reverse recovery current
- (3)  $t_{rr}$  reverse recovery time measured from zero crossing point of negative going  $I_F$  to point where a line passing through 0.75  $I_{RRM}$  and 0.50  $I_{RRM}$  extrapolated to zero current.
- (4)  $\mathbf{Q}_{\rm rr}$  area under curve defined by  $\mathbf{t}_{\rm rr}$  and  $\mathbf{I}_{\rm RRM}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

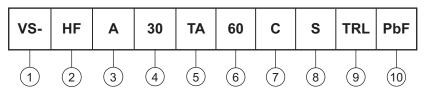
(5)  $dl_{(rec)M}/dt$  - peak rate of change of current during  $t_b$  portion of  $t_{rr}$ 

Fig. 10 - Reverse Recovery Waveform and Definitions



#### **ORDERING INFORMATION TABLE**

**Device code** 



- 1 Vishay Semiconductors product
- 2 HEXFRED® family
- Process designator: A = Electron irradiated
- 4 Current rating (30 = 30 A)
- Package outline (TA = TO-220, 3 leads)
- 6 Voltage rating (60 = 600 V)
- 7 Circuit configuration (C = Common cathode)
- S = D<sup>2</sup>PAK
- 9 • None = Tube
  - TRL = Tape and reel (left oriented)
  - TRR = Tape and reel (right oriented)
- • PbF = Lead (Pb)-free
  - P = Lead (Pb)-free (for D<sup>2</sup>PAK TRR and TRL)

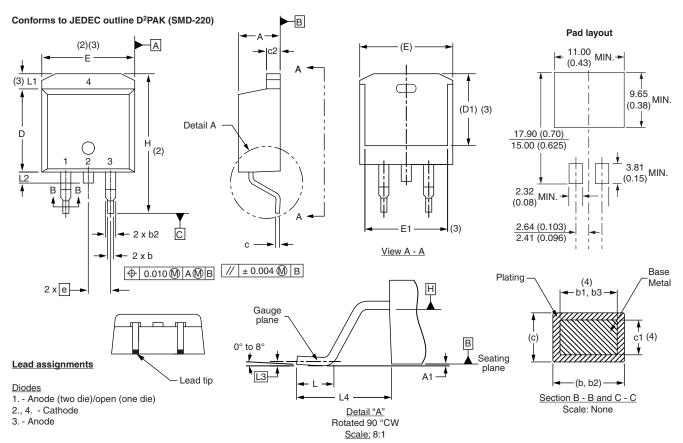
LINKS TO RELATED DOCUMENTS					
Dimensions	www.vishay.com/doc?95046				
Part marking information	www.vishay.com/doc?95054				
Packaging information	www.vishay.com/doc?95032				

ORDERING INFORMATION (Example)							
PREFERRED P/N	QUANTITY PER TUBE	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION				
VS-HFA30TA60CSPBF	50	1000	Antistatic plastic tube				
VS-HFA30TA60CSTRRP	800	800	13" diameter reel				
VS-HFA30TA60CSTRLP	800	800	13" diameter reel				



## D<sup>2</sup>PAK

#### **DIMENSIONS** in millimeters and inches



SYMBOL	MILLIN	IETERS	INC	NOTES	
STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190	
A1	0.00	0.254	0.000	0.010	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
С	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2

SYMBOL	MILLIM	ETERS	INCHES		NOTES
STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES
D1	6.86	8.00	0.270	0.315	3
Е	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
е	2.54 BSC		0.100 BSC		
Н	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	-	0.066	3
L2	1.27	1.78	0.050	0.070	
L3	0.25	BSC	0.010 BSC		
L4	4.78	5.28	0.188	0.208	

#### Notes

- $^{(1)}$  Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch
- (7) Outline conforms to JEDEC outline TO-263AB



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Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.

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